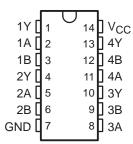
- Qualification in Accordance With AEC-Q100†
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- ESD Protection Exceeds 1500 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I<sub>CC</sub>

- Typical t<sub>pd</sub> = 8 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max

## D OR PW PACKAGE (TOP VIEW)



## description/ordering information

The 'HC02 device contains four independent 2-input NOR gates. They perform the Boolean function  $Y = \overline{A} + \overline{B}$  or  $Y = \overline{A} \bullet \overline{B}$  in positive logic.

#### ORDERING INFORMATION

TA	PACKAC	GE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - D	Tape and reel	SN74HC02QDRQ1	HC02QQ1
-40 C to 125 C	TSSOP - PW	Tape and reel	SN74HC02QPWRQ1	HC02QQ1

<sup>&</sup>lt;sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

## FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Х	L
Х	Н	L
L	L	Н

## logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>†</sup> Contact factory for details. Q100 qualification data available on request.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	86°C/W
PW package	
Storage temperature range, T <sub>stq</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	V	
	<b>_</b>	V <sub>CC</sub> = 2 V	1.5				
VIH		V <sub>CC</sub> = 4.5 V	3.15			V	
		V <sub>CC</sub> = 6 V	4.2				
		V <sub>CC</sub> = 2 V			0.5		
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35	V	
		V <sub>CC</sub> = 6 V			1.8		
٧ <sub>I</sub>	Input voltage		0		VCC	V	
VO	Output voltage		0		VCC	V	
		V <sub>CC</sub> = 2 V			1000		
Δt/Δν		V <sub>CC</sub> = 4.5 V			500	ns	
		V <sub>CC</sub> = 6 V			400		
TA	Operating free-air temperature		-40		125	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T <sub>A</sub> = 25°C		MIN	MAX	UNIT		
PARAMETER	TEST CONDITIO	ins .	VCC	MIN	TYP	MAX	IVIIIV	IVIAA	UNIT
	VOH $V_{I} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -20 \mu\text{A}$ $I_{OH} = -4 \text{ mA}$	2 V	1.9	1.998		1.9			
		I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		
Voн			6 V	5.9	5.999		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		
		I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1	
	$V_I = V_{IH}$ or $V_{IL}$		4.5 V		0.001	0.1		0.1	
VOL			6 V		0.001	0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V			2		40	μΑ
Ci			2 V to 6 V		3	10		10	pF

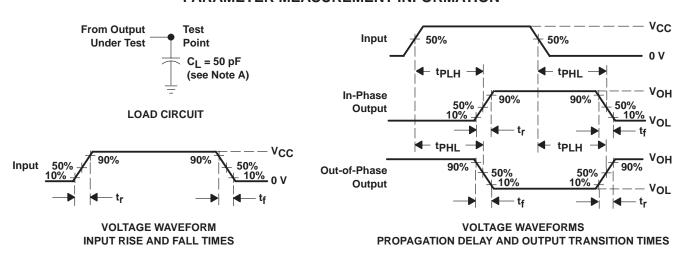
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	T,	4 = 25°C	;	MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	IVIIIV	IVIIIA IVIAA	UNIT
			2 V		45	90		135	
<sup>t</sup> pd	A or B	Y	4.5 V		9	18		27	ns
			6 V		8	15		23	
			2 V		38	75		110	
t <sub>t</sub>		Υ	4.5 V		8	15		22	ns
			6 V		6	13		19	

## operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	No load	22	pF

## PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

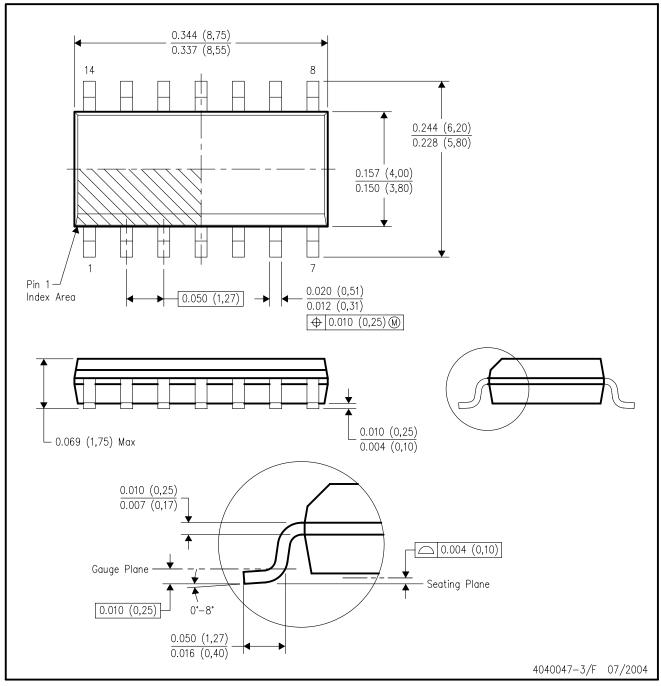
- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

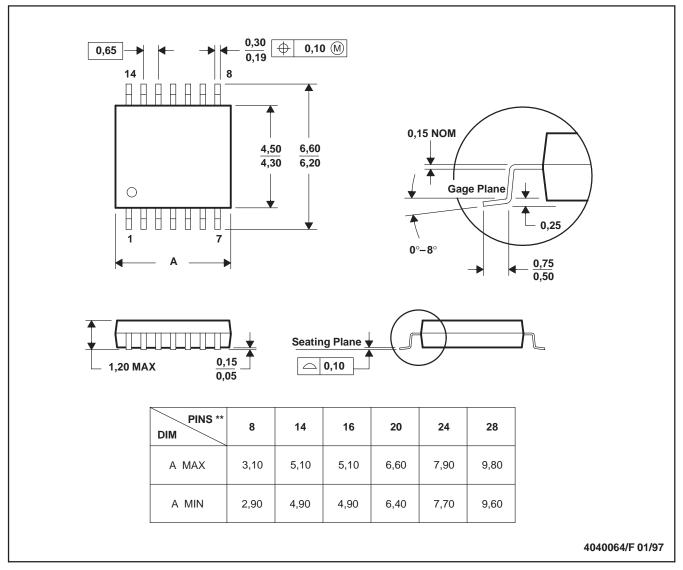
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



## PW (R-PDSO-G\*\*)

## 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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